

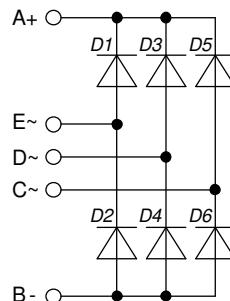
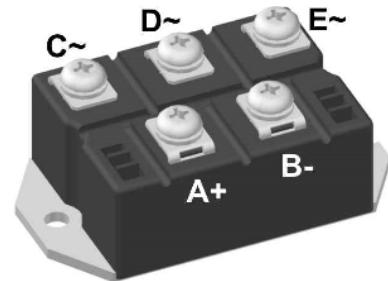
Standard Rectifier Module

3~ Rectifier
$V_{RRM} = 1600 \text{ V}$
$I_{DAV} = 240 \text{ A}$
$I_{FSM} = 2800 \text{ A}$

3~ Rectifier Bridge

Part number

VUO190-16NO7



 E72873

Features / Advantages:

- Package with DCB ceramic
- Improved temperature and power cycling
- Planar passivated chips
- Very low forward voltage drop
- Very low leakage current

Applications:

- Diode for main rectification
- For three phase bridge configurations
- Supplies for DC power equipment
- Input rectifiers for PWM inverter
- Battery DC power supplies
- Field supply for DC motors

Package: PWS-E

- Isolation Voltage: 3000 V~
- Industry standard outline
- RoHS compliant
- Easy to mount with two screws
- Base plate: Copper internally DCB isolated
- Advanced power cycling

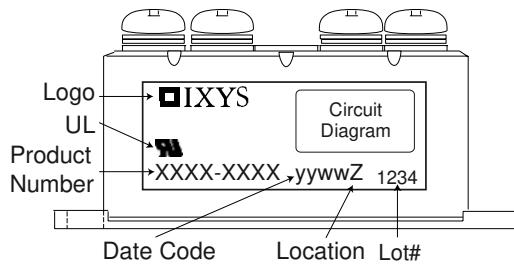
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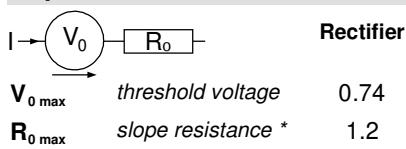
Rectifier

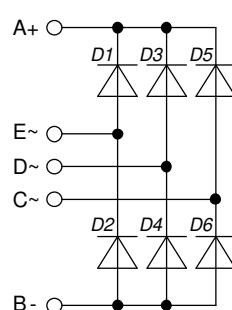
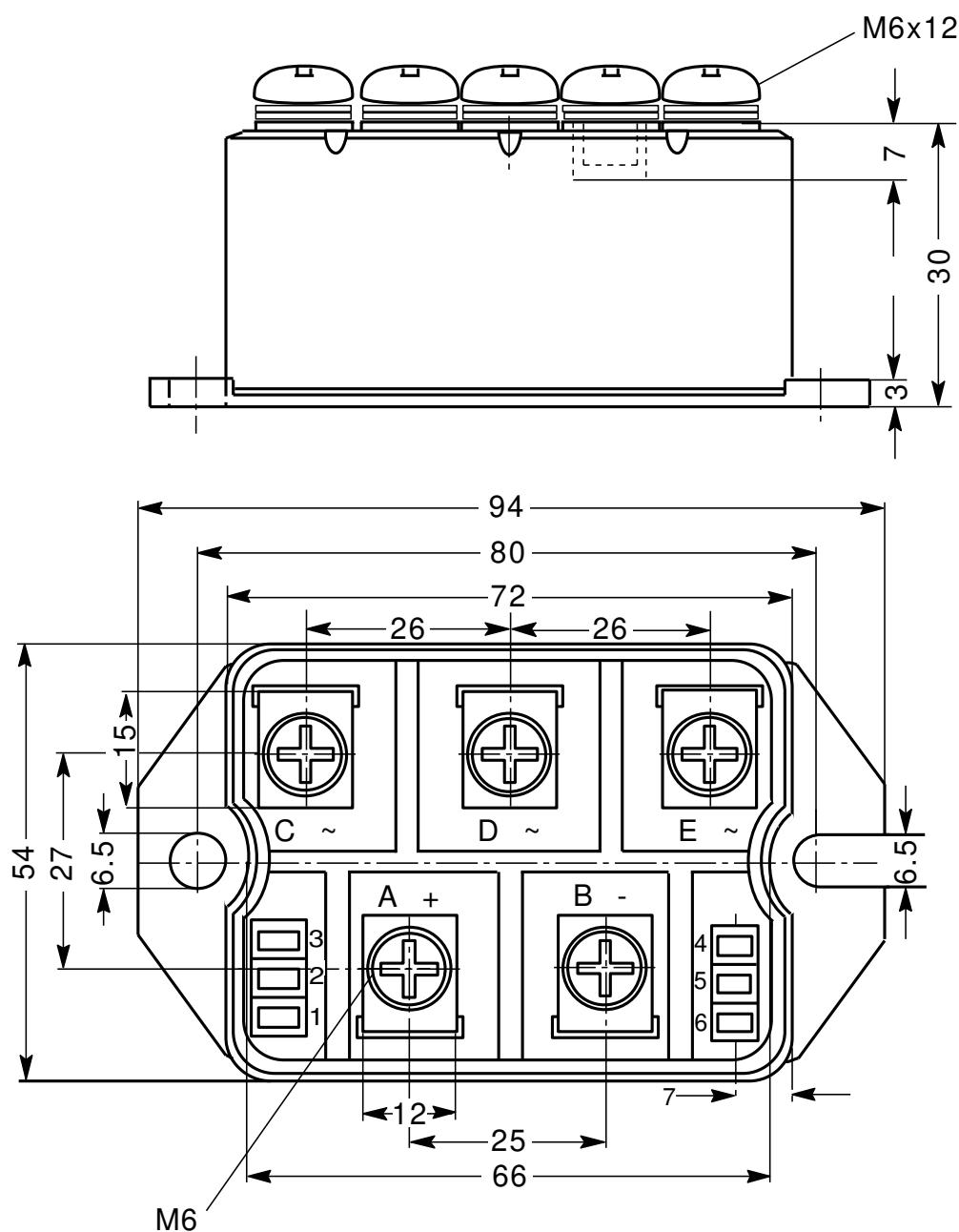
Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
V_{RSM}	max. non-repetitive reverse blocking voltage	$T_{VJ} = 25^\circ\text{C}$			1700	V
V_{RRM}	max. repetitive reverse blocking voltage	$T_{VJ} = 25^\circ\text{C}$			1600	V
I_R	reverse current	$V_R = 1600 \text{ V}$ $V_R = 1600 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 150^\circ\text{C}$		200 3.5	μA mA
V_F	forward voltage drop	$I_F = 80 \text{ A}$ $I_F = 240 \text{ A}$ $I_F = 80 \text{ A}$ $I_F = 240 \text{ A}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		1.07 1.36 0.96 1.33	V V V V
I_{DAV}	bridge output current	$T_C = 110^\circ\text{C}$ rectangular $d = \frac{1}{3}$	$T_{VJ} = 150^\circ\text{C}$		240	A
V_{F0} r_F	threshold voltage slope resistance } for power loss calculation only		$T_{VJ} = 150^\circ\text{C}$		0.74 2.4	V $\text{m}\Omega$
R_{thJC}	thermal resistance junction to case				0.4	K/W
R_{thCH}	thermal resistance case to heatsink			0.15		K/W
P_{tot}	total power dissipation		$T_C = 25^\circ\text{C}$		310	W
I_{FSM}	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$ $t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ\text{C}$ $V_R = 0 \text{ V}$ $T_{VJ} = 150^\circ\text{C}$ $V_R = 0 \text{ V}$		2.80 3.03 2.38 2.57	kA kA kA kA
I^2t	value for fusing	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$ $t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ\text{C}$ $V_R = 0 \text{ V}$ $T_{VJ} = 150^\circ\text{C}$ $V_R = 0 \text{ V}$		39.2 38.1 28.3 27.5	kA^2s kA^2s kA^2s kA^2s
C_J	junction capacitance	$V_R = 400 \text{ V}; f = 1 \text{ MHz}$	$T_{VJ} = 25^\circ\text{C}$	133		pF

Package PWS-E			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			250	A
T_{VJ}	virtual junction temperature		-40		150	°C
T_{op}	operation temperature		-40		125	°C
T_{stg}	storage temperature		-40		125	°C
Weight				284		g
M_D	mounting torque		4.25		5.75	Nm
M_T	terminal torque		4.25		5.75	Nm
$d_{Spp/App}$	creepage distance on surface / striking distance through air		terminal to terminal	12.0		mm
$d_{Spb/Apb}$			terminal to backside	26.0		mm
V_{ISOL}	isolation voltage	$t = 1$ second $t = 1$ minute	50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA	3000		V
				2500		V



Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	VUO190-16NO7	VUO190-16NO7	Box	5	462519

Equivalent Circuits for Simulation
* on die level
 $T_{VJ} = 150^\circ\text{C}$


Outlines PWS-E


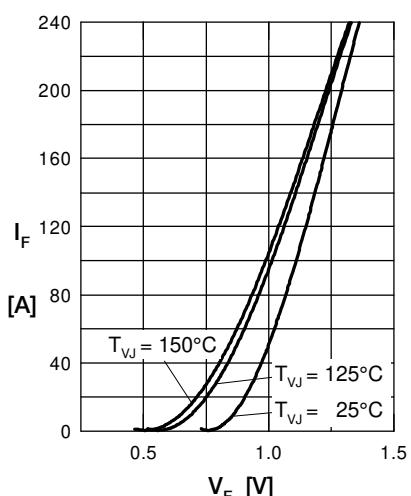
Rectifier


Fig. 1 Forward current vs.
voltage drop per diode

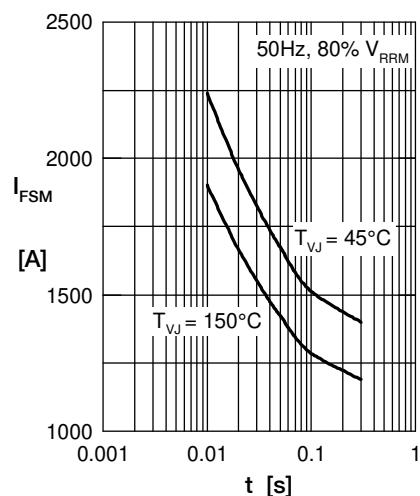


Fig. 2 Surge overload current
vs. time per diode

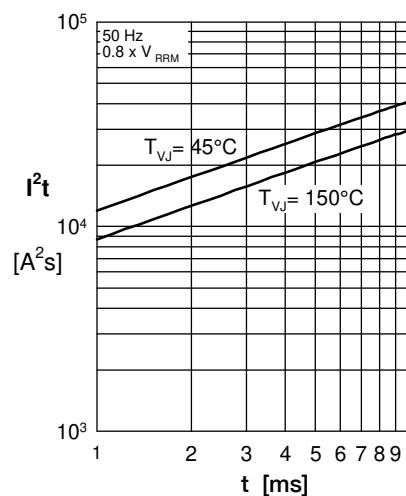


Fig. 3 I^2t vs. time per diode

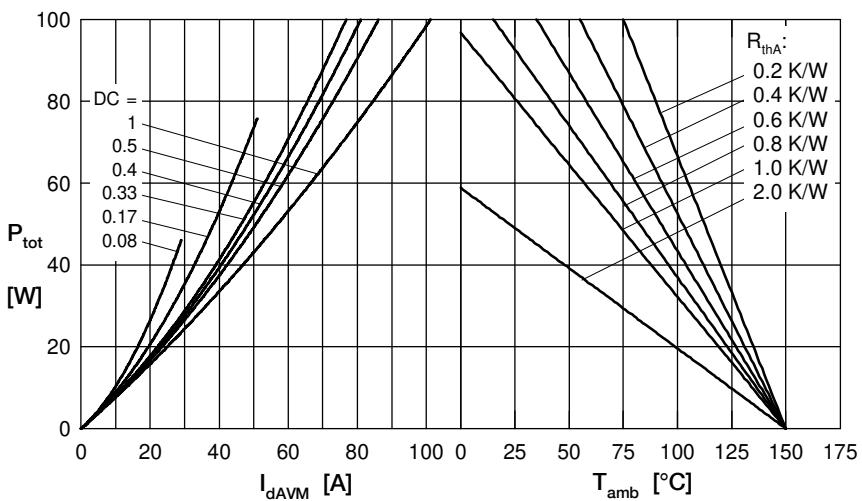


Fig. 4 Power dissipation vs. forward current
and ambient temperature per diode

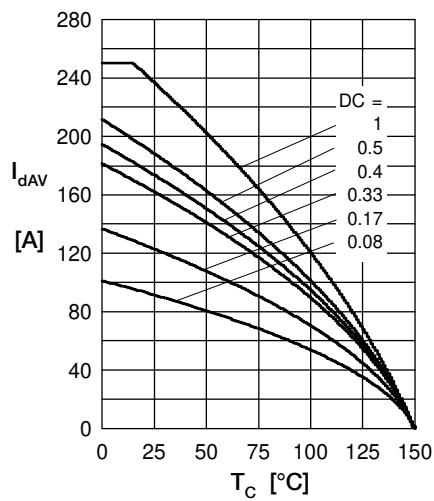


Fig. 5 Max. forward current vs.
case temperature per diode

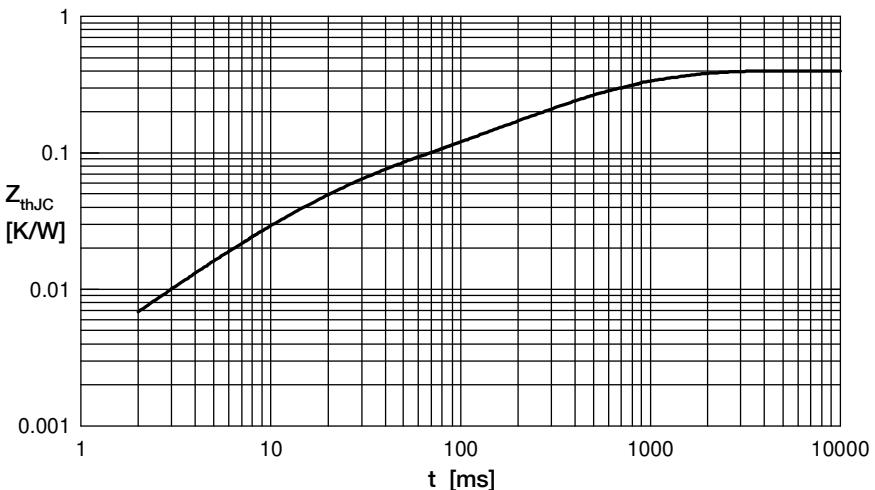


Fig. 6 Transient thermal impedance junction to case vs. time per diode

R_i	t_i
0.050	0.02
0.003	0.01
0.100	0.225
0.177	0.8
0.070	0.58